

Description

The PSM8N04R1H uses split gate trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. This device is suitable for power management and high efficiency applications at high switching frequencies applications.

MOSFET Product Summary

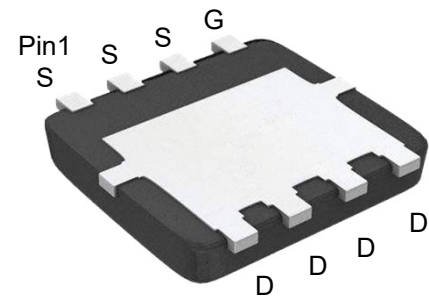
| $V_{DS}(V)$ | $R_{DS(on)}(m\Omega)(Typ)$ | $I_D(A)$ |
|-------------|----------------------------|----------|
| 40 | 1.2@ $V_{GS} = 10V$ | 212 |

Feature

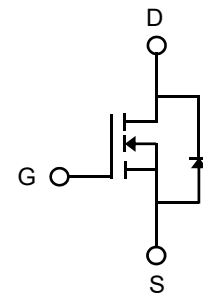
- Low $R_{DS(ON)}$ - Ensures On-State Losses are Minimized
- Excellent $Q_{gd} \times R_{DS(ON)}$ Product(FOM)
- Advanced Technology for DC-DC Converts
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- 100% UIS (Avalanche) Rated
- Lead-Free Finish ; RoHS Compliant
- Halogen and Antimony Free. "Green" Device

Applications

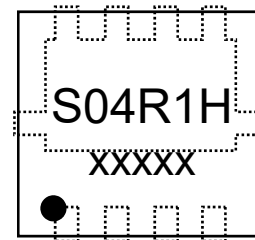
- PWM applications
- Load switch
- Power management
- DC-DC Converters
- Wireless Chargers



**PDFN5060-8L
(Bottom View)**



Circuit Diagram



**Pin1
Marking (Top View)**

Absolute maximum rating@25°C

| Rating | Symbol | Value | Units |
|--|-----------------|-------------------|--------------|
| Drain-Source Voltage | V_{DS} | 40 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous ¹⁾ | I_D | $T_C=25^\circ C$ | 212 |
| | | $T_C=100^\circ C$ | 134 |
| Pulsed Drain Current ²⁾ | I_{DM} | 850 | A |
| Total Power Dissipation | P_D | $T_C=25^\circ C$ | 104 |
| | | $T_C=100^\circ C$ | 42 |
| Avalanche Current @ $L=0.1mH$ | I_{AS} | 56 | A |
| Avalanche Energy @ $L=0.1mH$ ³⁾ | E_{AS} | 436 | mJ |
| Thermal Resistance , Junction-to-Case ⁵⁾ | $R_{\theta JC}$ | 1.2 | $^\circ C/W$ |
| Thermal Resistance Junction-to-Ambient ⁴⁾ | $R_{\theta JA}$ | 45 | $^\circ C/W$ |
| Junction and Storage Temperature Range | T_J, T_{STG} | -55~+150 | $^\circ C$ |

Electrical characteristics per line@25°C (unless otherwise specified)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Units | |
|--|---------------|--|---------------------|------|-----------|------------|---------|
| Off Characteristics⁶⁾ | | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS} = 0V, I_D = 250\mu A$ | 40 | - | - | V | |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 40V, V_{GS} = 0V$ | $T_J = 25^\circ C$ | - | - | 1.0 | μA |
| | | | $T_J = 125^\circ C$ | - | - | 100 | |
| Gate-Body Leakage Current | I_{GSS} | $V_{GS} = \pm 20V, V_{DS} = 0V$ | - | - | ± 100 | nA | |
| On Characteristics⁶⁾ | | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 2.0 | 3.0 | 4.0 | V | |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $V_{GS} = 10V, I_D = 20A$ | - | 1.2 | 1.4 | m Ω | |
| Forward Transconductance | g_{fs} | $V_{DS} = 5V, I_D = 20A$ | - | 34 | - | S | |
| Diode Forward Voltage | V_{SD} | $V_{GS} = 0V, I_S = 2A$ | - | 0.7 | 1.2 | V | |
| Dynamic Characteristics⁷⁾ | | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = 20V, V_{GS} = 0V, f = 1.0MHz$ | - | 3073 | - | μF | |
| Output Capacitance | C_{oss} | | - | 1515 | - | | |
| Reverse Transfer Capacitance | C_{rss} | | - | 58 | - | | |
| Gate Resistance | R_g | $V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$ | - | 1.4 | - | Ω | |
| Switching Characteristics⁷⁾ | | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DS} = 20V, V_{GS} = 10V, R_G = 3\Omega, I_D = 20A$ | - | 5.6 | - | ns | |
| Turn-on Rise Time | t_r | | - | 15 | - | | |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 20 | - | | |
| Turn-Off Fall Time | t_f | | - | 9.9 | - | | |
| Total Gate Charge @ $V_{GS} = 10V$ | Q_g | $V_{DS} = 20V, I_D = 20A, V_{GS} = 10V$ | - | 41 | - | nC | |
| Total Gate Charge @ $V_{GS} = 6V$ | | | - | 26 | - | | |
| Gate-Source Charge | Q_{gs} | | - | 14 | - | | |
| Gate-Drain Charge | Q_{gd} | | - | 7.5 | - | | |
| Gate Plateau Voltage | $V_{plateau}$ | | - | 5.0 | - | V | |
| Drain-Source Diode Characteristics⁶⁾ | | | | | | | |
| Reverse Recovery Time | t_{rr} | $I_F = 20A, d_i/d_t = 100A/\mu s$ | - | 46 | - | ns | |
| Reverse Recovery Charge | Q_{rr} | | - | 50 | - | nC | |
| Diode Forward Current | I_S | - | - | - | 132 | A | |

Notes:

1. This current is chip limited, which is calculated based on $R_{\theta JC}$
2. This current is calculated on single pulse with 10 μs Pulse & Duty Cycle = 1%.
3. Defined by design, not subject to production test, E_{AS} condition: $T_J = 25^\circ C, V_{DD} = 20V, V_{GS} = 10V, L = 1.0mH$.
4. Device mounted on FR-4 substrate PC board with 2oz copper in 1inch square cooling area.
5. Thermal resistance from junction to soldering point (on the exposed drain pad).
6. Short duration pulse test used to minimize self-heating effect.
7. Defined by design, not subject to production.

Typical Characteristics

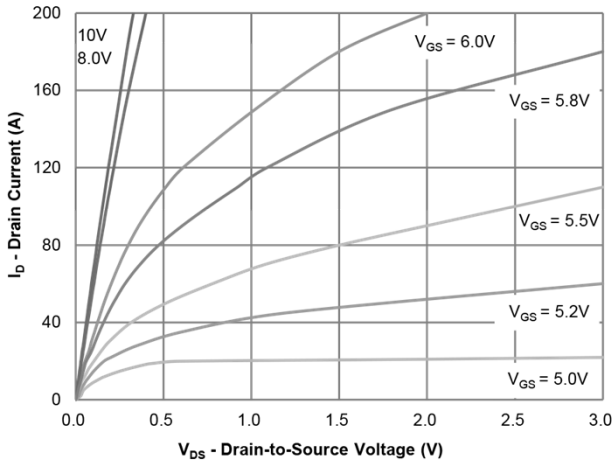


Figure 1: Output Characteristics

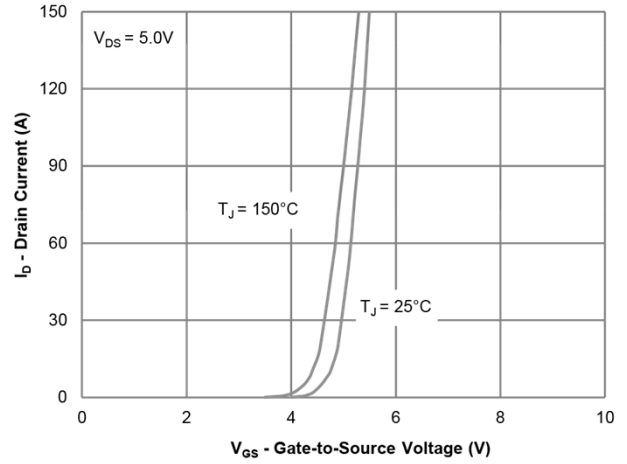


Figure 2: Transfer Characteristics

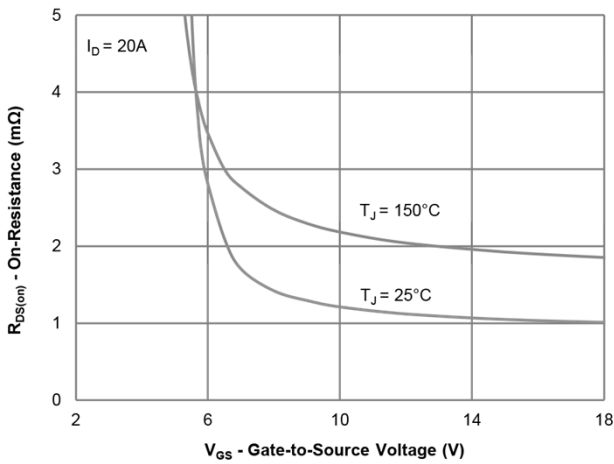


Figure 3: On-Resistance vs. Gate-Source Voltage

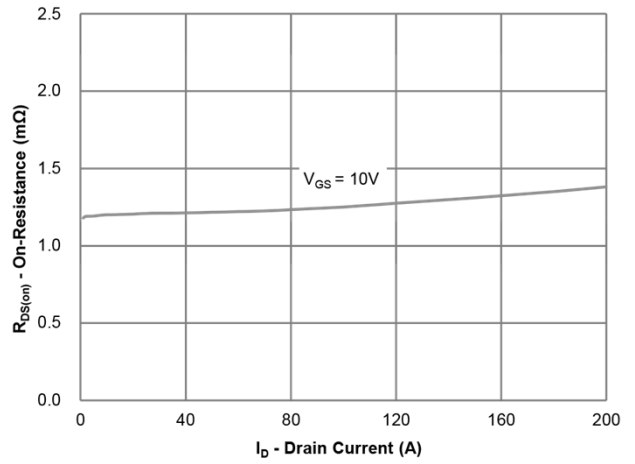


Figure 4: On-Resistance vs. Drain Current

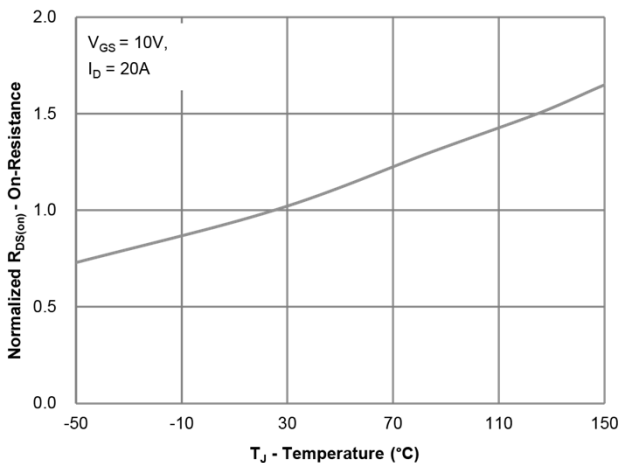


Figure 5: On-Resistance vs. Junction Temperature

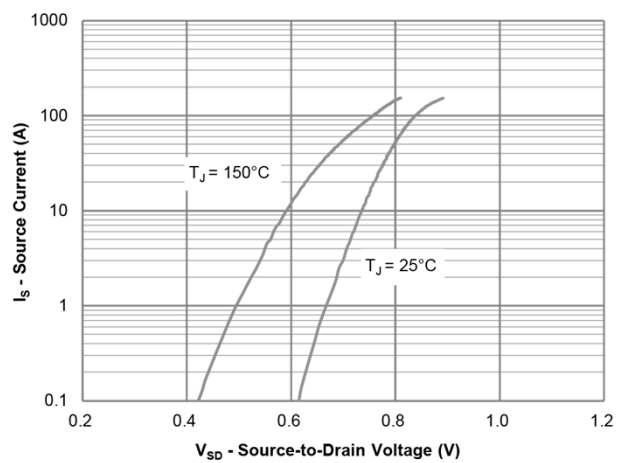


Figure 6: Source-Drain Diode Forward Voltage

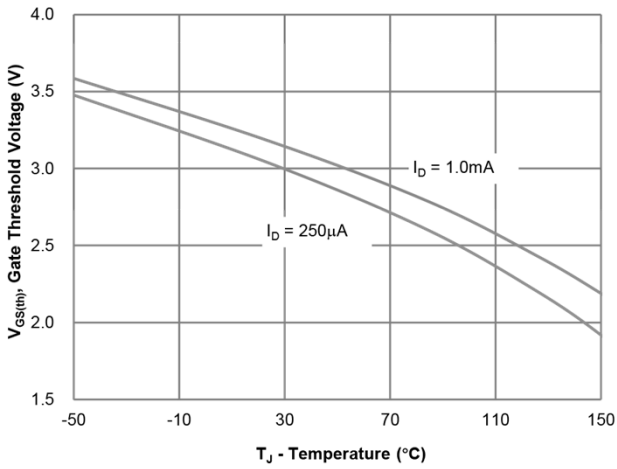


Figure 7: Gate Threshold Variation vs. Junction Temperature

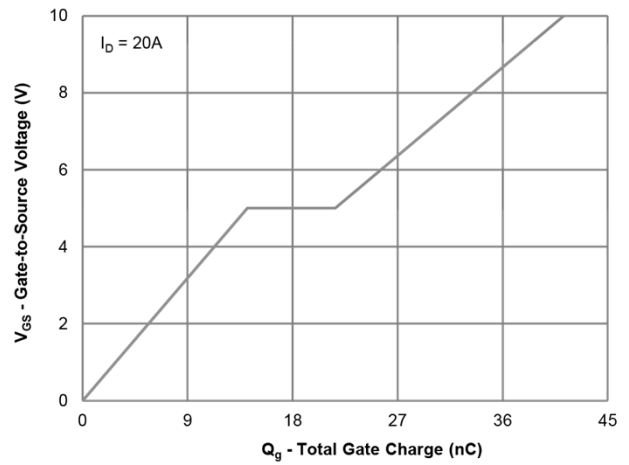


Figure 8: Gate Charge Characteristics

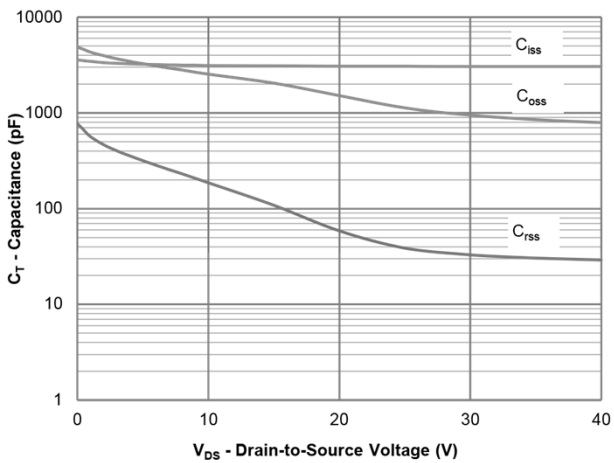


Figure 9: Capacitance Characteristics

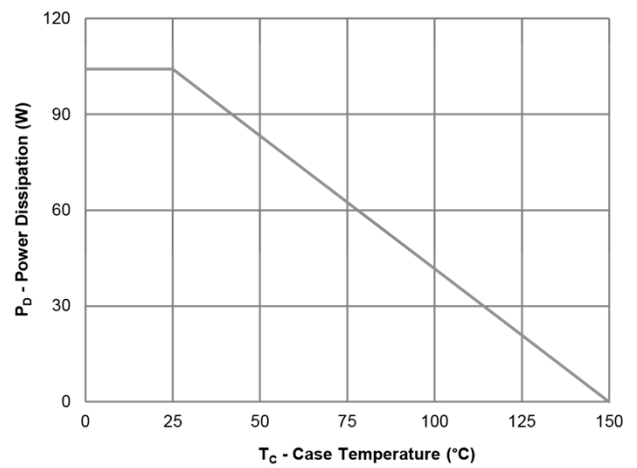


Figure 10: Power Derating

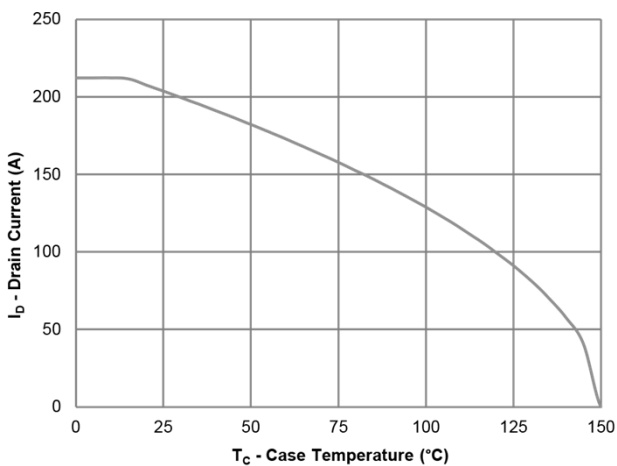


Figure 11: Current Derating

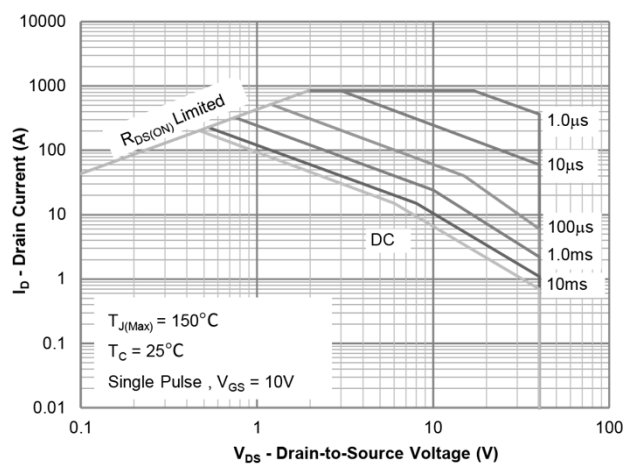


Figure 12: Safe Operating Area

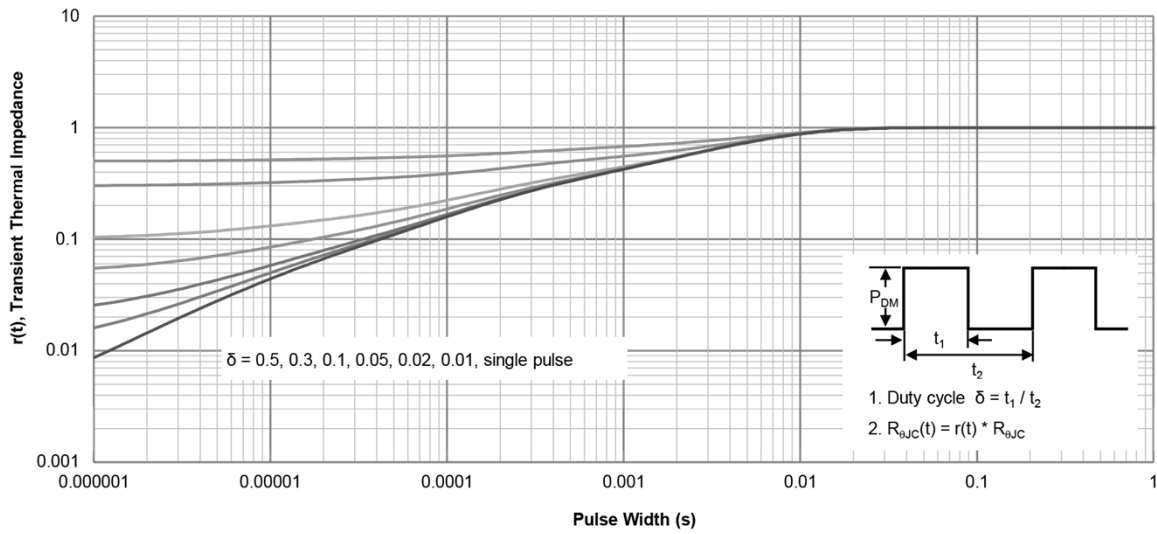
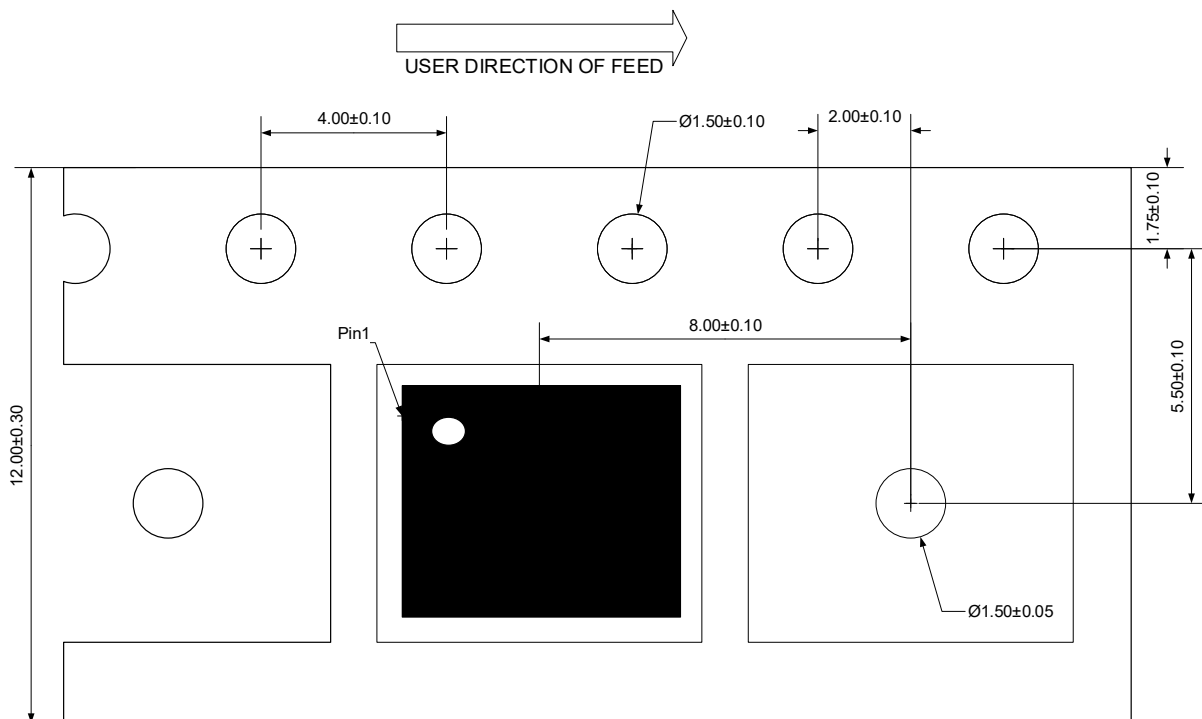


Figure 13: Normalized Maximum Transient Thermal Impedance

Ordering Information

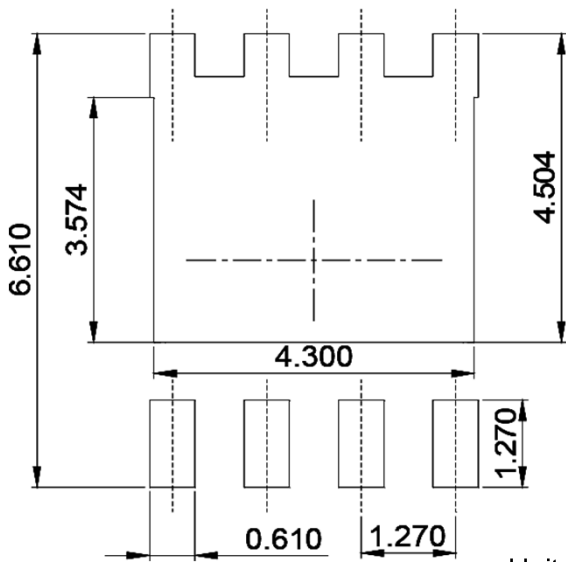
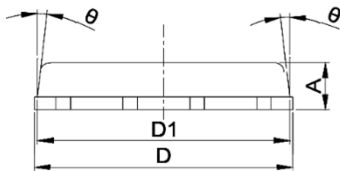
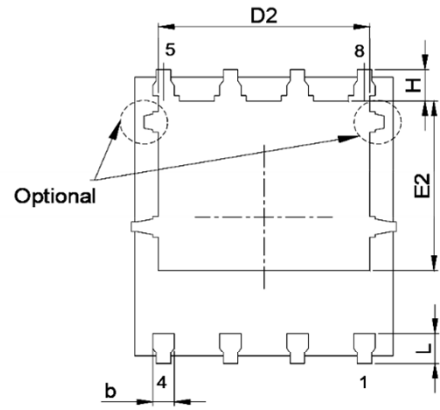
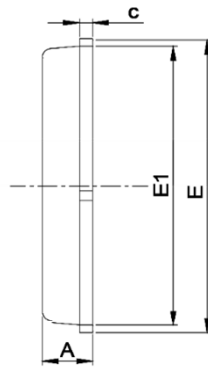
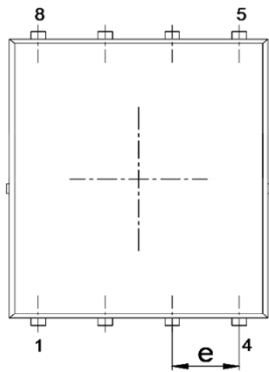
| Device | Package | Reel | Shipping |
|------------|-------------|------|--------------------|
| PSM8N04R1H | PDFN5060-8L | 13" | 5000 / Tape & Reel |

Load With Information



Unit:mm

Product Dimension (PDFN5060-8L)



Suggested PCB Layout

| Dim | Millimeters | | Inches | |
|-------|-------------|------|------------|-------|
| | Min | Max | Min | Max |
| A | 0.90 | 1.10 | 0.035 | 0.043 |
| b | 0.20 | 0.51 | 0.008 | 0.020 |
| c | 0.21 | 0.34 | 0.008 | 0.013 |
| D | 4.90 | 5.40 | 0.193 | 0.213 |
| D1 | 4.80 | 5.15 | 0.189 | 0.203 |
| D2 | 3.91 | 4.20 | 0.154 | 0.165 |
| E | 5.90 | 6.50 | 0.232 | 0.256 |
| E1 | 5.65 | 5.95 | 0.222 | 0.234 |
| E2 | 3.32 | 3.63 | 0.131 | 0.143 |
| e | 1.27 BSC. | | 0.050 Ref. | |
| H | 0.50 | 0.93 | 0.020 | 0.037 |
| L | 0.45 | 0.91 | 0.018 | 0.036 |
| theta | 0° | 12° | 0° | 12° |


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